



Material Content Data Sheet



Sales Product Name		TLS850B0TB V33		Issued		22. January 2018		
MA#		MA001655146						
Package		PG-TO263-5-1		Weight*		1670.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.422	0.09	0.09	851	851
leadframe	inorganic material	phosphorus	7723-14-0	0.145	0.01		87	
	non noble metal	iron	7439-89-6	0.483	0.03		289	
	non noble metal	copper	7440-50-8	482.096	28.85	28.89	288536	288912
	non noble metal	aluminium	7429-90-5	0.288	0.02	0.02	172	172
wire	non noble metal	aluminium	7429-90-5	0.288	0.02	0.02	172	172
encapsulation	organic material	carbon black	1333-86-4	1.461	0.09		874	
	plastics	epoxy resin	-	67.183	4.02		40209	
	inorganic material	silicondioxide	60676-86-0	661.607	39.59	43.70	395972	437055
leadfinish	non noble metal	tin	7440-31-5	12.370	0.74	0.74	7403	7403
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.243	0.01	0.01	145	146
solder	non noble metal	tin	7440-31-5	0.030	0.00		18	
	noble metal	silver	7440-22-4	0.038	0.00		23	
	non noble metal	lead	7439-92-1	1.441	0.09	0.09	863	904
heatspreader	inorganic material	phosphorus	7723-14-0	0.133	0.01		79	
	non noble metal	iron	7439-89-6	0.442	0.03		265	
	non noble metal	copper	7440-50-8	441.456	26.42	26.46	264213	264557
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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